

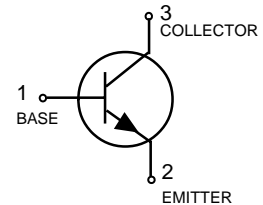
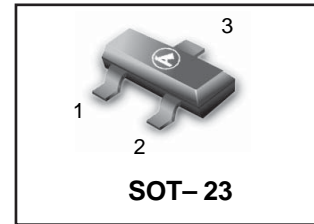
# General Purpose Transistors

Pb-Free package is available  
 S- Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

L2SC1623QLT1G Series  
 S-L2SC1623QLT1G Series

## DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
L2SC1623QLT1G S-L2SC1623QLT1G	L5	3000/Tape&Reel
L2SC1623QLT3G S-L2SC1623QLT3G	L5	10000/Tape&Reel
L2SC1623RLT1G S-L2SC1623RLT1G	L6	3000/Tape&Reel
L2SC1623RLT3G S-L2SC1623RLT3G	L6	10000/Tape&Reel
L2SC1623SLT1G S-L2SC1623SLT1G	L7	3000/Tape&Reel
L2SC1623SLT3G S-L2SC1623SLT3G	L7	10000/Tape&Reel



## MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	$V_{CEO}$	50	V
Collector-Base Voltage	$V_{CBO}$	60	V
Emitter-Base Voltage	$V_{EBO}$	7	V
Collector current-continuoun	$I_C$	150	mAdc

## THERMAL CHARATEERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (1) $T_A=25^{\circ}C$ Derate above $25^{\circ}C$	$P_D$	225 1.8	mW mW/ $^{\circ}C$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	556	$^{\circ}C/W$
Total Device Dissipation Alumina Substrate, (2) $T_A=25^{\circ}C$ Derate above $25^{\circ}C$	$P_D$	300 2.4	mW mW/ $^{\circ}C$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	417	$^{\circ}C/W$
Junction and Storage Temperature	$T_J, T_{stg}$	-55 to +150	$^{\circ}C$

1. FR-5 = 1.0 x 0.75 x 0.062 in.

2. Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina.

## DEVICE MARKING

L2SC1623QLT1G=L5    L2SC1623RLT1G=L6    L2SC1623SLT1G=L7

## ELECTRICAL CHARACTERISTICS ( $T_A=25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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### OFF CHARACTERISTICS

Collector Cutoff Current ( $V_{CB}=60V$ )	$I_{CBO}$	-	-	0.1	$\mu A$
Emitter Cutoff Current ( $V_{EB}=5V$ )	$I_{EBO}$	-	-	0.1	$\mu A$

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**Series**

**ON CHARACTERISTICS**

DC Current Gain ( $I_C=1.0\text{mA}$ , $V_{CE}=6\text{V}$ )	$h_{FE}$	120	-	560	
Collector-Emitter Saturation Voltage ( $I_C=100\text{mA}$ , $I_B=10\text{mA}$ )	$V_{CE(sat)}$	-	0.15	0.3	V
Base-Emitter Saturation Voltage ( $I_C=100\text{mA}$ , $I_B=10\text{mA}$ )	$V_{BE(sat)}$	-	0.86	1.0	V
Base -Emitter On Voltage ( $I_C=1\text{mA}$ , $V_{CE}=6.0\text{V}$ )	$V_{BE}$	0.55	0.62	0.65	V

**SMALL-SIGNAL CHARACTERISTICS**

Current-Gain-Bandwidth Product ( $V_{CE}=6.0\text{V}$ , $I_E=-10\text{mA}$ )	$F_t$	-	250	-	MHz
Output Capacitance( $V_{CE}=6\text{V}$ , $I_E=0$ , $f=1.0\text{MHz}$ )	$C_{ob}$	-	3	-	Pf

**$h_{FE}$  Values are classified as follows**

NOTE:

*	Q	R	S
$h_{FE}$	120~270	180~390	270~560

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Fig.1 Grounded emitter propagation characteristics

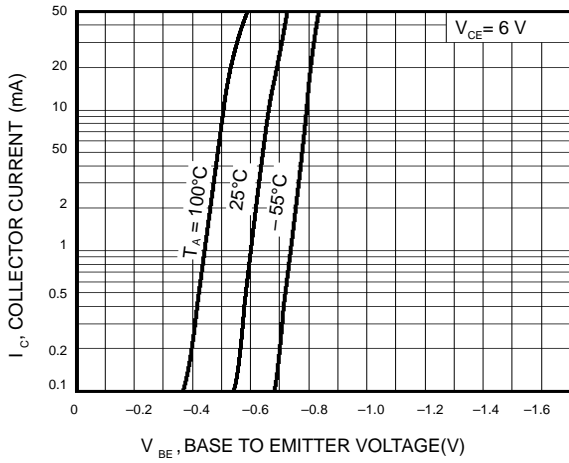


Fig.2 Grounded emitter output characteristics(I)

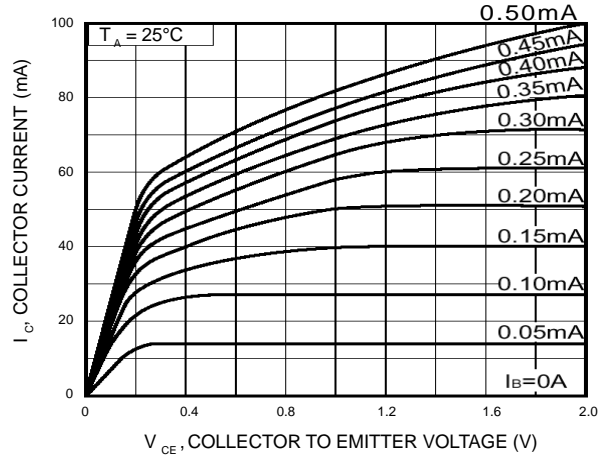


Fig.3 Grounded emitter output characteristics(II)

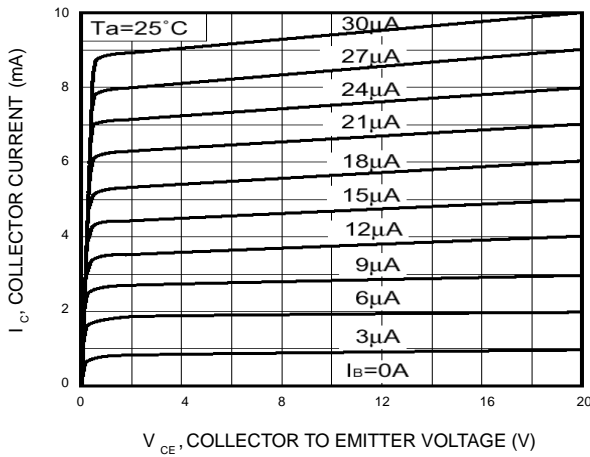


Fig.4 DC current gain vs. collector current (I)

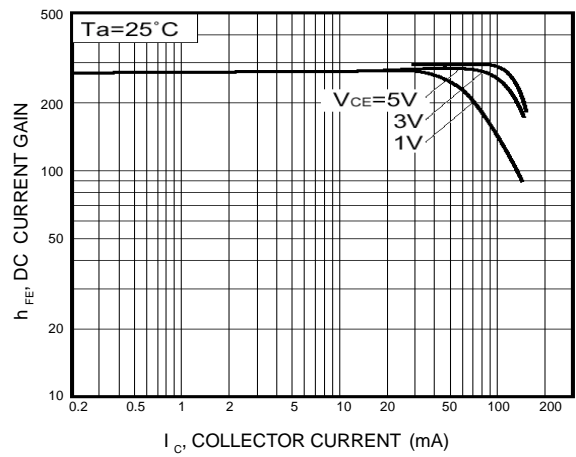


Fig.5 DC current gain vs. collector current (II)

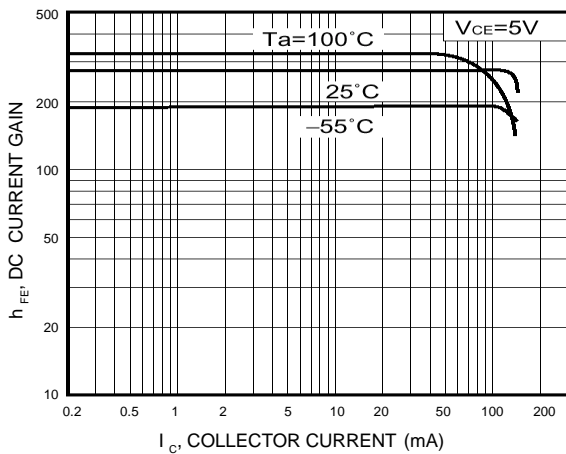
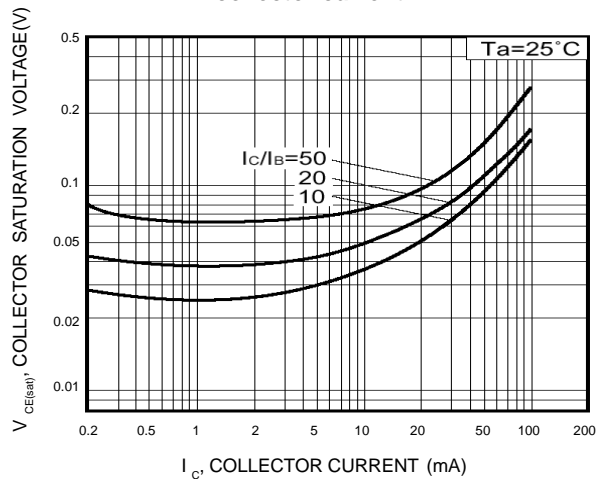


Fig.6 Collector-emitter saturation voltage vs. collector current



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Fig.7 Collector-emitter saturation voltage vs. collector current (I)

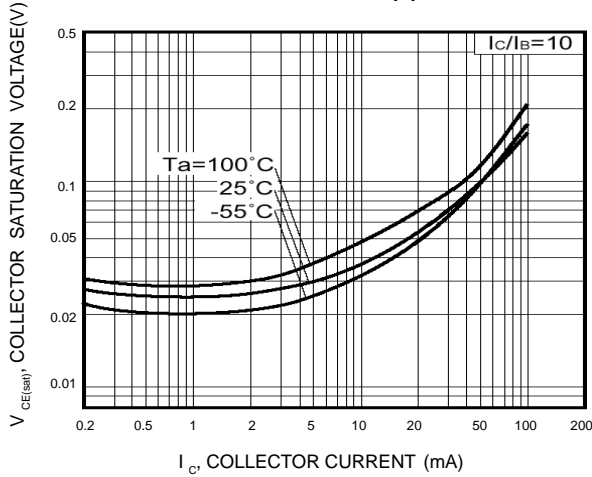


Fig.8 Collector-emitter saturation voltage vs. collector current (II)

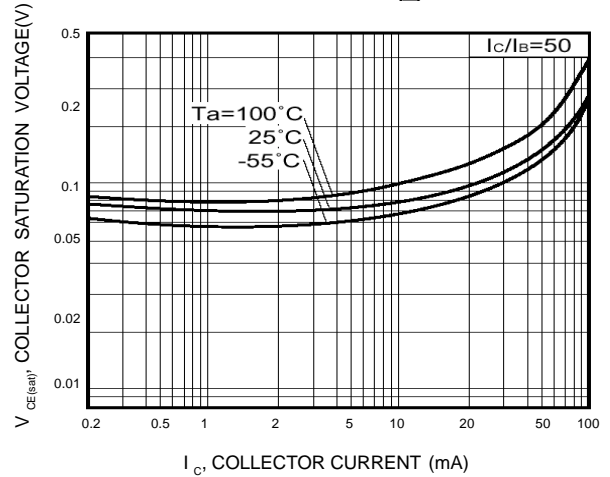


Fig.9 Gain bandwidth product vs. emitter current

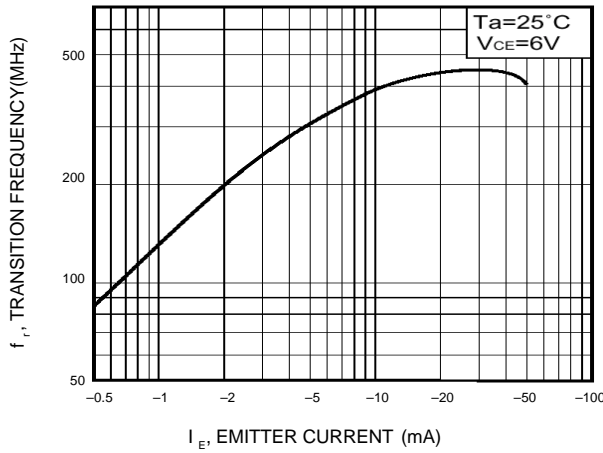


Fig.10 Collector output capacitance vs. collector-base voltage  
Emitter input capacitance vs. emitter-base voltage

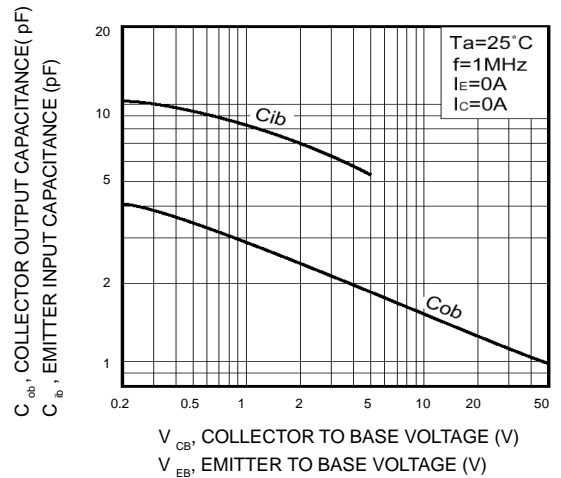
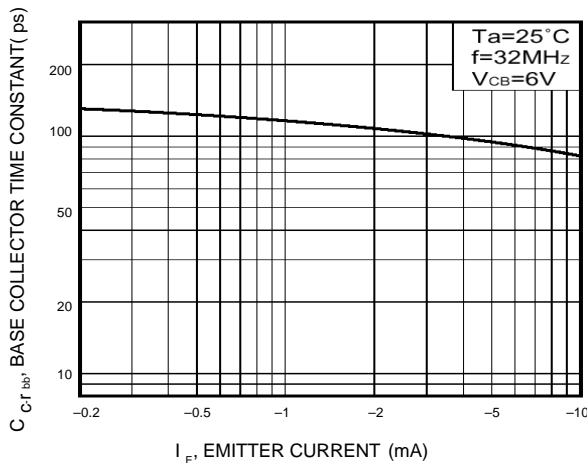
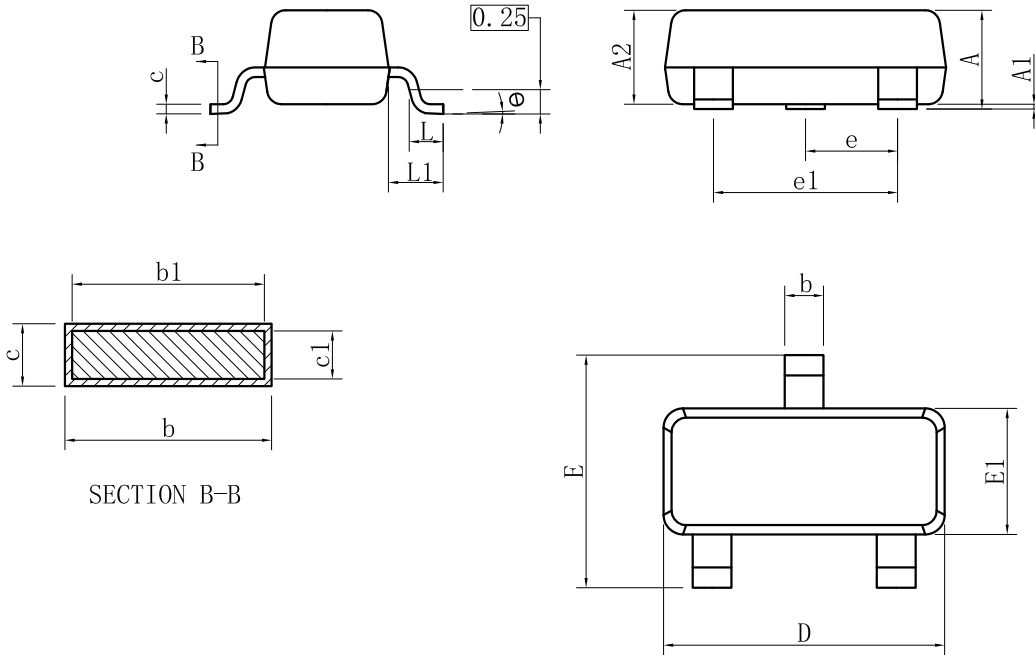


Fig.11 Base-collector time constant vs. emitter current



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OUTLINE AND DIMENSIONS

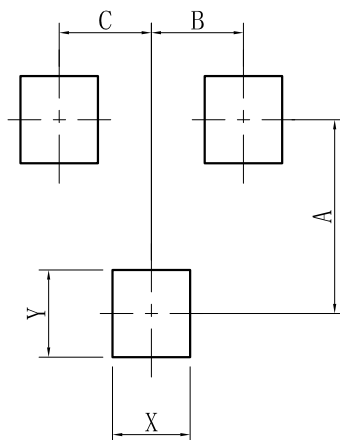


SOT23			
DIM	MIN	NOR	MAX
A	0.89	-	1.12
A1	0.01	-	0.10
A2	0.88	0.95	1.02
b	0.30	-	0.50
b1	0.30	0.40	0.45
c	0.08	-	0.20
c1	0.08	0.10	0.16
D	2.80	2.90	3.04
E	2.10	-	2.64
E1	1.20	1.30	1.40
e	0.95BSC		
e1	1.90BSC		
L	0.40	0.46	0.60
L1	0.54REF		
θ	0°	-	8°
All Dimensions in mm			

GENERAL NOTES

1. Top package surface finish Ra0.4±0.2um
2. Bottom package surface finish Ra0.7±0.2um
3. Side package surface finish Ra0.4±0.2um

SOLDERING FOOTPRINT



SOT-23	
DIM	(mm)
X	0.80
Y	0.90
A	2.00
B	0.95
C	0.95

**DISCLAIMER**

- Curve guarantee in the specification. The curve of test items with electric parameter is used as quality guarantee. The curve of test items without electric parameter is used as reference only.
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